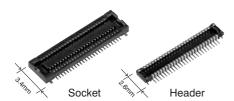
Panasonic ideas for life

Narrow pitch connectors (0.35mm pitch)

For board-to-FPC

F35S Series

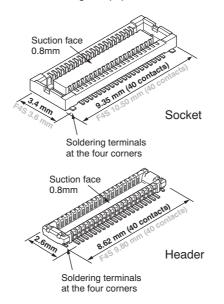




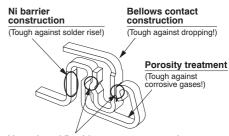
FEATURES

1. Space-saving design (0.35 mm pitch)

The footprint when mated is down approx. 15% from our existing F4S model (40 contacts), contributing to the functionality enhancement and size reduction of target equipment.



2. Strong resistance to adverse environments **TDUSH CONTRCT** construction



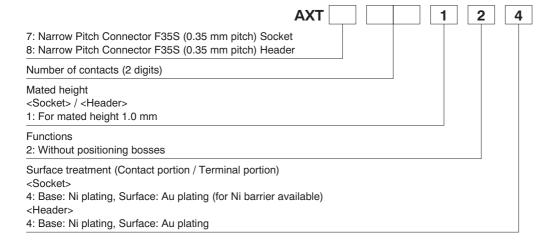
V notch and Double contact constructions
(Tough against foreign particles and flux!)

- 3. The soldering terminals at the four corners enhance the mounting strength.
- 4. The simple lock structure ensures a superior mating/unmating operation feel.
- 5. The gull-wing-shaped terminals facilitate imaging inspections.

APPLICATIONS

Particularly suitable for board-to-FPC connections in ultra-compact mobile equipment that requires size and thickness reduction and functionality enhancement

ORDERING INFORMATION



PRODUCT TYPES ** TOUGH CONTRCT

Mated height	Number of contacts	Part number		Packing		
		Socket	Header	Inner carton	Outer carton	
1.0mm	40	AXT740124	AXT840124		6,000 pieces	
	50	AXT750124	AXT850124			
	60	AXT760124	AXT860124	3,000 pieces		
	70	AXT770124	AXT870124			
	80	AXT780124	AXT880124			

- Notes: 1. Order unit: For mass production: in 1-inner-box (1-reel) units
 Samples for mounting check: in 50-connector units. Please contact our sales office.

 2. The above part numbers are for connectors without positioning bosses, which are standard. When ordering connectors with positioning bosses, please contact our sales office.

 3. Please contact us for connectors having a number of contacts other than those listed above.

SPECIFICATIONS

1. Characteristics

Item		Specifications	Conditions
	Rated current	0.25A/contact (Max. 4 A at total contacts)	
Electrical characteristics	Rated voltage	60V AC/DC	
	Breakdown voltage	150V AC for 1 min.	No short-circuiting or damage at a detection current of 1 mA when the specified voltage is applied for one minute.
	Insulation resistance	Min. 1,000M Ω (initial)	Using 250V DC megger (applied for 1 min.)
	Contact resistance	Max. 100mΩ	Based on the contact resistance measurement method specified by JIS C 5402.
	Composite insertion force	Max. 0.981N/contacts × contacts (initial)	
Mechanical	Composite removal force	Min. 0.165N/contacts × contacts	
characteristics	Contact holding force (Socket contact)	Min. 0.49N/contacts	Measuring the maximum force. As the contact is axially pull out.
	Ambient temperature	−55°C to +85°C	No freezing at low temperatures. No dew condensation.
Environmental characteristics	Soldering heat resistance	Peak temperature: 260°C or less (on the surface of the PC board around the connector terminals)	Infrared reflow soldering
		300°C within 5 sec. 350°C within 3 sec.	Soldering iron
	Storage temperature	-55°C to +85°C (product only) -40°C to +50°C (emboss packing)	No freezing at low temperatures. No dew condensation.
	Thermal shock resistance (header and socket mated)	5 cycles, insulation resistance min. 100M Ω , contact resistance max. 100m Ω	Sequence 155.\(\gamma^\circ\), 30 minutes 2. \(\circ\), Max. 5 minutes 3. 85\(\gamma^\circ\), C, 30 minutes 4. \(\circ\), Max. 5 minutes
	Humidity resistance (header and socket mated)	120 hours, insulation resistance min. 100M Ω , contact resistance max. 100m Ω	Bath temperature 40±2°C, humidity 90 to 95% R.H.
	Saltwater spray resistance (header and socket mated)	24 hours, insulation resistance min. 100M Ω , contact resistance max. 100m Ω	Bath temperature 35±2°C, saltwater concentration 5±1%
	H ₂ S resistance (header and socket mated)	48 hours, contact resistance max. $100 \text{m}\Omega$	Bath temperature 40±2°C, gas concentration 3±1 ppm, humidity 75 to 80% R.H.
Lifetime characteristics	Insertion and removal life	50 times	Repeated insertion and removal speed of max. 200 times/ hours
Unit weight		40-contact type: Socket: 0.04 g Header: 0.02 g	

2. Material and surface treatment

Part name	Material	Surface treatment
Molded portion	LCP resin (UL94V-0)	_
Contact and Post	Copper alloy	Contact portion: Base: Ni plating, Surface: Au plating Terminal portion: Base: Ni plating, Surface: Au plating (except the terminal tips) The socket terminals close to the portion to be soldered have nickel barriers (exposed nickel portions). Soldering terminals: Sockets: Base: Ni plating, Surface: Pd+Au flash plating (except the terminal tips) Headers: Base: Ni plating, Surface: Au plating (except the terminal tips)

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DIMENSIONS

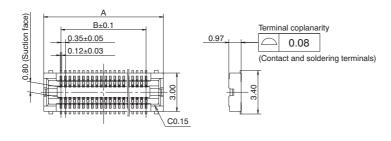
Interested in CAD data? You can obtain CAD data for all products with a mark from your local Panasonic Electric Works representative.

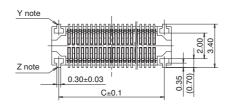
(Unit: mm)

Socket (Mated height: 1.0 mm)









General tolerance: ±0.2

Dimension table (mm)

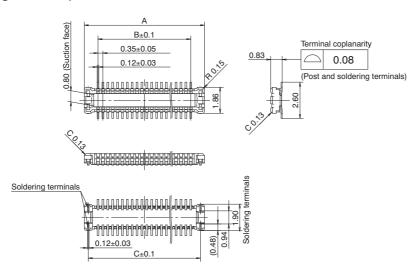
· ,						
Number of contacts/ dimension	А	В	С			
40	9.35	6.65	8.25			
50	11.10	8.40	10.00			
60	12.85	10.15	11.75			
70	14.60	11.90	13.50			
80	16.35	13.65	15.25			

Note: Since the soldering terminals are built into the body, the sections Y and Z are electrically connected.

Header (Mated height: 1.0 mm)





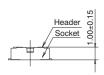


General tolerance: ±0.2

Dimension table (mm)

Number of contacts/ dimension	А	В	С
40	8.62	6.65	8.05
50	10.37	8.40	9.80
60	12.12	10.15	11.55
70	13.87	11.90	13.30
80	15.62	13.65	15.05

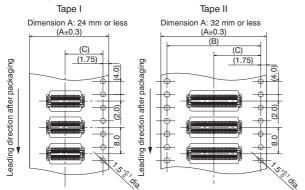
• Socket and Header are mated



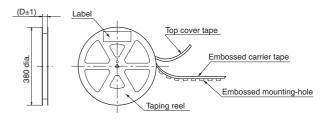
EMBOSSED TAPE DIMENSIONS (Unit: mm) (Common to all sockets and headers)

Specifications for taping

(In accordance with JIS C 0806-1990. However, not applied to the mounting-hole pitch of some connectors.)



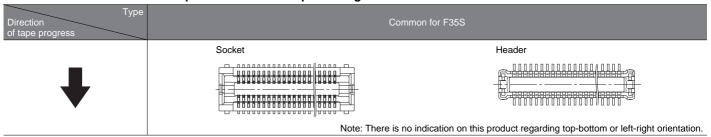
• Specifications for the plastic reel (In accordance with EIAJET-7200B.)



• Dimension table (Unit: mm)

Type/Mated height	Number of contacts	Type of taping	А	В	С	D	Quantity per reel
Common for sockets and headers:	40 to 70	Tape I	24.0	_	11.5	25.4	3,000
1.0mm	80	Tape II	32.0	28.4	14.2	33.4	3,000

• Connector orientation with respect to embossed tape feeding direction



NOTES

1. Regarding the design of PC board patterns

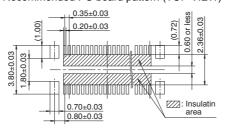
Conduct the recommended foot pattern design, in order to preserve the mechanical strength of terminal solder areas.

2. Recommended PC board and metal mask patterns

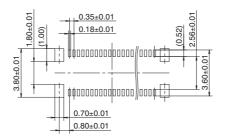
Appropriate control of solder amount is required to minimize solder bridges and other defects for connectors with 0.35-mm, 0.4-mm or 0.5-mm pitch terminals, which require high-density mounting. Refer to the right-hand drawing for recommended patterns.

• Socket (Mated height: 1.0 mm)

Recommended PC board pattern (TOP VIEW)

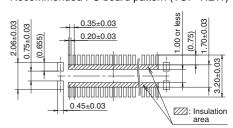


Recommended metal mask opening pattern Metal mask thickness: When 120μm (Terminal opening ratio: 65%) (Metal-part opening ratio: 100%)



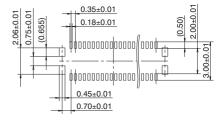
• Header (Mated height: 1.0 mm)

Recommended PC board pattern (TOP VIEW)



Recommended metal mask opening pattern Metal mask thickness: When 120μm (Terminal opening ratio: 60%)

(Metal-part opening ratio: 100%)



For Cautions for Use, see Connector Technical Information. For other details, please verify with the product specification sheets.